Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) ~~Movement~~ A movement detector having six degrees of freedom comprising:~~comprising~~

a support; and

~~on which~~ three position sensors ~~are~~ arranged on the support according to three orthogonal axes, each sensor comprising:~~comprising~~

-a rigid body having two opposing inside walls;

-conducting areas arranged on the rigid body, the conducting areas comprising four conducting areas arranged such that two of the conducting areas are arranged on one of the inside walls and two of the conducting areas are arranged on the opposing inside wall; and

an electrically conducting deformable element that is ~~presenting a rest position in which it is~~ isolated from the conducting areas when the deformable element is in a rest position, and the deformable element moving from the rest position to an active position in response to a high-speed movement of predetermined direction and orientation, ~~detector wherein each sensor comprises four conducting areas arranged two by two on two opposite inside walls of the rigid body~~

wherein ~~and that~~ the deformable element associated with each sensor is in equilibrium around ~~its central~~ a central part of the deformable element,

wherein the deformable element responds~~, responds~~ to a translation along a predetermined axis by bending, causing ends of the deformable element to substantially simultaneously and temporarily ~~causing a simultaneous and temporary~~ contact ~~of its ends with the~~ two conducting areas ~~of one and the~~on a same inside wall, and ~~and~~

wherein the deformable element responds to a rotation around a predetermined axis by ~~a pivoting~~ pivoting, causing the ends of the deformable element to substantially simultaneously and temporarily ~~a simultaneous and temporary~~ contact ~~of its ends with~~ two conducting areas arranged on ~~opposite~~ opposing inside walls.

2. (Currently Amended) ~~Detector~~The detector according to claim 1, further comprising an electronic processing circuit connected to the conducting areas of the three sensors.

3. (Currently Amended) ~~Detector~~ The detector according to claim 1, wherein the deformable element is a beam in equilibrium around ~~its transverse~~a transverse median axis of the beam.

4. (Currently Amended) ~~Detector~~ The detector according to claim 3, wherein the beam comprises conducting areas ~~at the ends thereof~~ arranged at the ends of the beam.

5. (Currently Amended) ~~Detector~~ The detector according to claim 1, wherein the deformable element is a disc in equilibrium around ~~its central axis~~a central axis of the disc.

6. (Currently Amended) ~~Detector~~ The detector according to claim 5, wherein the disc comprises a peripheral conducting area on each ~~of its faces~~face of the disc.

7. (Currently Amended) ~~Detector~~ The detector according to claim 1, wherein the deformable element of each of the three sensors is electrically connected to a power supply contact area arranged on the rigid body of the corresponding sensor.

8. (Currently Amended) ~~Detector~~ The detector according to claim 1, wherein the deformable element of each of the three sensors is in an equilibrium position corresponding to the rest position of the corresponding sensor for any movement having an acceleration ~~the acceleration whereof is~~ less than or equal to the force of gravity G.

9. (Currently Amended) ~~Detector~~ The detector according to claim 1, wherein the rigid body of each of the three sensors ~~a sensor~~ comprises two substrates arranged face to

face, connected by balls constituting an electrical interconnection between the conducting areas of one of the substrates and output electrical contact areas formed on the other substrate.

10. (Currently Amended) ~~Detector~~ The detector according to claim 9, wherein the deformable element ~~is formed by~~ includes two deformable half-elements, each of the deformable half-elements corresponding to one of the substrates and comprising a conducting ~~layer,~~ layer, the conducting layer being supported by a central pillar,

wherein the central pillar is formed on a central power supply contact area~~area,~~ that is formed on the corresponding substrate.

11. (Currently Amended) ~~Method~~ A method for production of each of the three sensors~~a sensor~~ according to claim 10, achieved by microelectronics techniques, the method comprising ~~and comprises~~:

~~—~~forming conducting areas and power supply areas on each of the substrates;~~formation on each of the substrates of conducting areas, of power supply contact areas and, on one of the substrates, of output electrical contact areas,~~

forming an output electrical contact areas on one of the substrates;

~~—~~forming a central pillar on each of the substrates, the central pillar contacting the power supply contact area and supporting a conducting layer that serves as the deformable half-element; ~~formation on each of the substrates of a central pillar, in contact with the power supply contact area and supporting a conducting layer designed to form a deformable half-element,~~

installing balls on the output electrical contact areas; and

~~—~~installation of balls on the output electrical contact areas,

hybridizing the two substrates arranged face to face.

~~—~~hybridization of the two substrates arranged face to face.